Facts and Figures

- 2006: Start of DGS at DISCO HI-TEC EUROPE in Munich
- 2009 & 2013: Cleanroom extensions due to increasing demand and capacity limits
- Since 2016: Per month more than 12,000 processed wafers
- Since June 2018: Cleanroom extension of 800 m² – total processing area: 1330 m²
- Shift service: 2 shifts / 7 days a week

Part of global semiconductor development through advanced dicing-grinding services.

Contact

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Why dicing-grinding service by DISCO?

DISCO HI-TEC EUROPE’s Dicing-Grinding Service (DGS) is an integral component of any manufacturing stage when it comes to high-precision processing of ICs, MEMS, LEDs, other micro components and their inspection/metrology. As a complete service, DGS implements exact customer requirements as well as develops ideal material handling.

Typical materials we process:
- Silicon and other semiconductors
- Sapphire
- Quartz
- Glass
- Bonded Materials
- GaAs
- SiC
- Ceramics
- QFN / Lead frame
- FR4
- Compound materials
- Other materials on-demand

DGS Quality Management system is DIN EN ISO 9001 and DIN EN ISO 14001 certified and all processes are subject to strict controls.